

ASM International N.V. to Host 32 nm Interconnect Technology Seminar

BILTHOVEN, the Netherlands, May 29, 2007 – ASM International N.V. (NASDAQ: ASMI and Euronext Amsterdam: ASM) will host a seminar on 32nm Interconnect Technology and Beyond to be held on the evening of June 5, 2007, at the Hyatt Regency San Francisco Airport, in Burlingame, CA 94010, USA. This seminar is in conjunction with the IEEE International Interconnect Technology Conference (IITC).

Guest speakers at the ASM seminar are: Dr. Yoshihiro Hayashi of NEC Corporation presenting on *“Methodology for Structure Control of Advanced Porous Low-K Dielectrics”*; Dr. Jean Michailos of STMicroelectronics on *“PEALD Materials for RF, Analog and Decoupling MIM Capacitors”*; and Charles J. Vath of ASM Pacific Technology Ltd. who will discuss Advanced Packaging, *“Space – The Final Frontier.”* The presentations will be followed by a poster session on other advanced technologies, such as ASM’s NCP, Gap-fill, and Ru/Cu materials.

Those interested in attending this seminar should e-mail IITC.Seminar@asm.com by June 1st.

About ASM International

ASM International N.V. and its subsidiaries design and manufacture equipment and materials used to produce semiconductor devices. The company provides production solutions for wafer processing (Front-end segment) as well as assembly and packaging (Back-end segment) through facilities in the United States, Europe, Japan and Asia. ASM International's common stock trades on NASDAQ (symbol ASMI) and the Euronext Amsterdam Stock Exchange (symbol ASM). For more information, visit ASMI's web site at www.asm.com.

Safe Harbor Statement under the U.S. Private Securities Litigation Reform Act of 1995: All matters discussed in this statement, except for any historical data, are forward-looking statements. Forward-looking statements involve risks and uncertainties that could cause actual results to differ materially from those in the forward-looking statements. These include, but are not limited to, economic conditions and trends in the semiconductor industry generally and the timing of the industry cycles specifically, currency fluctuations, the timing of significant orders, market acceptance of new products, competitive factors, litigation involving intellectual property, shareholder and other issues, commercial and economic disruption due to natural disasters, terrorist activity, armed conflict or political instability, epidemics, and other risks indicated in the Company's filings from time to time with the U.S. Securities and Exchange Commission, including, but not limited to, the Company's reports on Form 20-F and Form 6-K. The Company assumes no obligation nor intends to update or revise any forward-looking statements to reflect future developments or circumstances.

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